

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-29 (canceled).

Claim 30 (currently amended): A ~~defective~~ semiconductor package assembly comprising:

(a) ~~a defective substrate having a first surface with a pattern of conductors~~ a support element comprising a plurality of individual functional substrates and at least one individual defective substrate, wherein the defective substrate has a first surface with a defective pattern of conductors and a second surface including a defective die attach site;

~~(b) — the defective substrate having a second surface including a defective die attach site;~~

(e) ~~(b)~~ a wire bond slot forming an opening through the defective substrate extending from the first surface of the defective substrate to the second surface of the defective substrate; and

~~(d)~~ ~~(c)~~ a cover member attached to the defective substrate on the second surface so as to cover at least a portion of the opening, wherein the cover member does not comprise a functional die.

Claim 31 (currently amended): The ~~defective~~ semiconductor package assembly of claim 30, wherein the cover member comprises tape.

Claim 32 (currently amended): The ~~defective~~ semiconductor package assembly of claim 30, wherein the cover member covers a majority of the opening.

Claims 33-35 (canceled)

Claim 36 (currently amended): The ~~defective~~ semiconductor package assembly of claim 30, wherein the cover member covers from about 70% to about 98% of the opening formed by the wire bond slot.

Claim 37 (currently amended): The ~~defective~~ semiconductor package assembly of claim 30, wherein the wire bond slot is associated with the defective die attach site.

Claim 38 (currently amended): The ~~defective~~ semiconductor package assembly of claim 30, wherein the cover member comprises a defective die.

Claim 39 (currently amended): The ~~defective~~ semiconductor package assembly of claim 30, wherein the cover member covers from about 80% to about 90% of the opening formed by the wire bond slot.

Claim 40 (currently amended): The ~~defective~~ semiconductor package assembly of claim 30, wherein the cover member covers at least about 70% of the opening formed by the wire bond slot.

Claim 41 (new): The semiconductor package assembly of claim 30, further comprising a functional die attached to each functional substrate.

Claim 42 (new): The semiconductor package assembly of claim 30, further comprising a material encapsulating the cover member.

Claim 43 (new): A semiconductor assembly, comprising:

(a) a plurality of individual functional substrates and at least one individual defective substrate, wherein the defective substrate has a defective pattern of conductors associated with a defective die attach site;

(b) a wire bond slot forming an opening through the defective substrate extending from a first surface of the defective substrate to a second surface of the defective substrate;

(c) a cover member attached to the defective substrate on the first surface or the second surface so as to cover at least a portion of the opening, wherein the cover member does not comprise a functional die.

Claim 44 (new): The semiconductor assembly of claim 43, wherein the functional substrates and the defective substrate are integrally connected.

Claim 45 (new): The semiconductor assembly of claim 43, wherein the wire bond slot is associated with the defective die attach site.

Claim 46 (new): The semiconductor assembly of claim 45, further comprising a functional die attached to each functional substrate.

Claim 47 (new): The semiconductor assembly of claim 46, further comprising a material encapsulating the cover member.